

Substitute for form 1449A/PTO

FEB 11 2002

**INFORMATION DISCLOSURE  
STATEMENT BY APPLICANT**  
(use as many sheets as necessary)**COMPLETE IF KNOWN**

Application Number	09/386,734
Confirmation Number	1242
Filing Date	August 31, 1999
First Named Inventor	Ritzdorf et al.
Group Art Unit	1742
Examiner Name	G. Wyszomierski

Sheet

1

of

2

Attorney Docket No. 29195.8170US

**U.S. PATENT DOCUMENTS**

*EXAMINER INITIALS*	Cite No.	U.S. Patent Document		Name of Patentee or Applicant of Cited Document	Date of Publication of Cited Document	Pages, Columns, Lines, Where Relevant Passages or Relevant Figures Appear
		NUMBER	Kind Code (if known)			
Aw		4,539,222		Anderson, Jr. <i>et al</i>	9/3/1985	
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		5,600,532		Michiya <i>et al</i>	2/4/1997	
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		5,893,752		Zhang <i>et al</i>	4/13/1999	
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TC 1700**FOREIGN PATENT DOCUMENTS**

*EXAMINER INITIALS*	Cite No.	Foreign Patent Document			Name of Patentee or Applicant of Cited Document	Date of Publication of Cited Document	Pages, Columns, Lines, Where Relevant Passages or Relevant Figures Appear	T
		Office	Number	Kind Code (if known)				
Aw		EP	0 751 567 A2		Intl. Business Machines Corp.	1/2/1997		
Aw		EP	0 881 673 A2		Intl. Business Machines Corp.	12/2/1998		
Aw		EP	0 982 771 A1		Lucent Technologies Inc.	3/1/2000		
Aw		WO	98/27585		Intl. Business Machines Corp.	6/25/1998		

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G. Wyszomierski

DATE CONSIDERED

9/9/02

\* EXAMINER: Initial if reference considered, whether or not criteria is in conformance with MPEP 609. Draw line through citation if not in conformance and not considered. Include copy of this form with next communication to applicant(s).

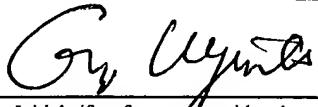
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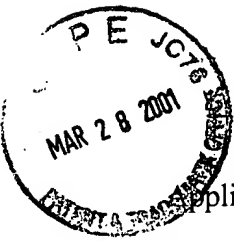
PTO/SB/08A

Approved for use through 10/31/99. OMB 0651-0031  
Patent and Trademark Office: U.S. DEPARTMENT OF COMMERCE

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Sheet	2	of	2				
<b>OTHER PRIOR ART-NON PATENT LITERATURE DOCUMENTS</b>							
*EXAMINER INITIALS*	Cite No.	Include name of the author (in CAPITAL LETTERS), title of the article (when appropriate), title of the item (book, magazine, journal, serial, symposium, catalog, etc.), date, page(s), volume/issue number(s), publisher, city and/or country where published.					
Gu		STOYCHEV, D.S., TOMOV, V., VITANOVA, I.B., "Recovery And Recrystallization Of Electrodeposited Bright Copper Coatings At Room Temperature. I Microhardness in relation to Coating Structure", <i>Journal of Applied Electrochemistry</i> , 15, 879-886. Chapman and Hall Ltd. (1985).					
		Harper, J.M.E., Rodbell, K.P., "Microstructure control in semiconductor metallization", <i>J. Vac. Sci. Technol. B</i> 15(4), pp. 763-779, Jul/Aug 1997.					
		Gangulee, A., "The Structure of Electroplated and Vapor-Deposited Copper Films", <i>J. Appl. Phys.</i> , Vol. 43, No. 3, pp. 867-873, March 1972.					
		Gangulee, A., "Structure of Electroplated and Vapor-Deposited Copper Films III. Recrystallization and Grain Growth", <i>J. Appl. Phys.</i> , Vol. 45, No. 9, pp. 3749-3756, September 1974.					
		Gross, M.E. et al, "Microstructure and Texture of Electroplated Copper in Damascene Structures", <i>Material Research Society Proceedings</i> , Vol. 514, 1998.					
		Edelstein, D. et al, "Full Copper Wiring in a Sub-0.25µm CMOS ULSI Technology", <i>IEEE</i> , pp. 773-776, 1997					
		Ryan, J.G. et al, "Technology Challenges for Advanced Interconnects", Date Unknown.					
		Lowenheim, Frederick, "Electroplating", pp. 416-425, January 1979.					
Gu		Patent Abstracts of Japan 04-120290, 21 April 1992.					

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INFORMATION CITED BY APPLICANTS THAT MAY BE MATERIAL TO THE PROSECUTION OF THE SUBJECT APPLICATION

Applicants: T.L. Ritzdorf et al. Attorney Docket No. SEMT116048  
Application No.: 09/386,734 Group Art Unit: 1742  
Filed: August 31, 1999 Examiner: G. Wyszomierski  
Title: METHOD AND APPARATUS FOR LOW TEMPERATURE ANNEALING OF METALLIZATION MICROSTRUCTURES IN THE PRODUCTION OF A MICROELECTRONIC DEVICE

U.S. PATENT DOCUMENTS

*Examiner Initial	ID	Document No.	Date	Name
<u>GW</u>	U4	5,747,355	05/05/1998	Konuma et al.
<u>GW</u>	U5	5,779,799	07/14/1998	Davis
<u>GW</u>	U6	6,099,712	08/08/2000	Ritzdorf et al.
<u>GW</u>	U7	6,100,195	08/08/2000	Chan et al.
<u>GW</u>	U8	6,136,163	10/24/2000	Cheung et al.

Examiner

Date Considered

G Wyszomierski

6/14/01

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U.S. PATENT DOCUMENTS

*Examiner Initial	ID	Document No.	Date	Name
<u>Gw</u>	U1	5,091,339	02/1992	Carey
<u>Qu</u>	U2	5,677,244	10/1997	Venkatraman
<u>Gw</u>	U3	5,873,992	02/1999	Glezen et al.

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*Examiner Initial	ID	Document No.	Date	Country	Yes	No
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None

OTHER INFORMATION

(Including Author, Title, Date, Pertinent Pages, Etc.)

*Examiner Initial	ID
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None

Examiner	Date Considered
<u>G Wyszomierski</u>	<u>6/14/01</u>

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